

# 24<sup>th</sup> Annual Components for Military & Space Electronics Conference & Exhibition

April 19-23, 2021

VIRTUAL CONFERENCE



## Call for Presentations

The premier event focused on the design, reliability, and application of electronic components for use in avionics, aerospace, military & commercial space systems. Three days of technical talks with cutting edge tutorials on monday and friday.

You are requested to submit an outline for a virtual presentation at CMSE conducted remotely from your dektop on topics such as:

- Leveraging Component Specs: Automotive vs. Commercial vs Mil Aerospace Component Capability
- IC Copper Wire Bonding & Reliability
- EEE Parts Engineering Issues for Small Sats
- Supercapacitors and high CV for High Rel Applications
- PME/BME MLCCs for Hi-Rel Applications
- GaN and SiC for RF and Power Management
- SIP 2.5- 3D and Wafer Level Packaging WLP
- Artificial Intelligence (AI) Quantum Computing applications and next generation microelectronics
- ITAR issues and emerging technologies
- Reliability/Volumetric efficiency/Cost trade-offs, e.g. Non-Hermetic vs. Hermetic.
- Approaches for Assessing Reliability of COTS Electronic Cards and Assemblies
- Trust and security issues in supply chain management
- Digital Engineering

## Deadline for Submission: January 15, 2021

Presentations are 15 minutes with 5 minutes of Q & A. The CMSE committee does not require a formal paper submission. You decide how much of the presentation material to provide the attendee. The idea is to promote sharing of basic scientific and technical information about common problems faced by both the component manufacturer and the system OEM.

Please email your presentation outline to [info@tjgreenllc.com](mailto:info@tjgreenllc.com).



**Tom Green**  
*Chair*

**Tom Terlizzi**  
*Exhibits Chair*

**Leon Hamiter**  
*Components Technology Institute*

**Ron Hardesty**  
*Northrup Grumman Space Systems*

**Ron Demcko**  
*AVX Corp.*

**Aaron DerMarderosian**  
*Raytheon Intelligence and Space*

**Bob Lowry**  
*Electronic Materials Consultant*

**Larry Harzstark**  
*Aerospace*

**Andy Moor**  
*Northrop Grumman Space Systems*

**Tomáš Zedníček**  
*EPCI European Passive Component Institute*

**Rick Rodriguez**  
*Raytheon Missiles and Defense*

**Sultan Ali Lilani**  
*Integra Technologies LLC*

**Yuri Freeman**  
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**Peter Majewicz**  
*NASA*

**Allyson D. Yarbough, PhD**  
*Aerospace*

**Anthony Casasnovas**  
*Honeywell Aerospace*